

L Number	Hits	Search Text	DB	Time stamp
2	65	prevent adj slippage and 451/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/17 06:38
3	656	prevent adj slippage same grip\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/17 06:39
4	5	(prevent adj slippage same grip\$3) and 279/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/17 06:40
5	4131	friction near3 grip\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/17 06:41
6	27	(friction near3 grip\$3) and 451/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/17 06:41
7	8	friction near3 grip\$3 same wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/11/17 06:42
-	0	carrier adj head same membrane same rough\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/24 07:11
-	48	carrier adj head and membrane and rough\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/24 07:29
-	811	membrane near2 (textur\$2 or rough\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/24 07:31
-	6	(membrane near2 (textur\$2 or rough\$4)) and carrier adj head	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/24 07:29
-	40	membrane near2 (textur\$2 or rough\$4)	USOCR	2003/10/24 07:30
-	1	(membrane near2 (textur\$2 or rough\$4)) and 279/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/24 07:31
-	88	(membrane near2 (textur\$2 or rough\$4)) and (semiconductor or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/24 07:34
-	259	(rough\$3 near2 surface) near2 grip\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/24 07:49

-	0	((rough\$3 near2 surface) near2 grip\$4) and carrier adj head	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/24 07:36
-	1	((rough\$3 near2 surface) near2 grip\$4) and (semiconductor or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/24 07:36
-	542	(textur\$3 near2 surface) near2 grip\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/24 07:50
-	0	((textur\$3 near2 surface) near2 grip\$4) and carrier adj head	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/24 07:50
-	2	((textur\$3 near2 surface) near2 grip\$4) and (semiconductor or wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/24 07:50
-	36	((textur\$3 near2 surface) near2 grip\$4) and membrane	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/24 07:52
-	948	grip\$4 near2 wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/24 07:53
-	71	(grip\$4 near2 wafer) and 451/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/24 07:54
-	70	(grip\$4 near2 wafer) and 438/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/24 07:58
-	14	(grip\$4 near2 wafer) and 216/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/24 08:02